

CD4020BMS, CD4024BMS, CD4040BMS

CMOS Ripple-Carry Binary Counter/Dividers

FN3300  
Rev 1.00  
October 1996

**Features**

- High Voltage Types (20V Rating)
- Medium Speed Operation
- Fully Static Operation
- Buffered Inputs and Outputs
- 100% Tested for Quiescent Current at 20V
- Standardized Symmetrical Output Characteristics
- Common Reset
- 5V, 10V and 15V Parametric Ratings
- Maximum Input Current of 1 $\mu$ A at 18V Over Full Package-Temperature Range;
  - 100nA at 18V and 25 $^{\circ}$ C
- Noise Margin (Over Full Package Temperature Range):
  - 1V at VDD = 5V
  - 2V at VDD = 10V
  - 2.5V at VDD = 15V
- Meets All Requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications For Description Of 'B' Series CMOS Devices"

**Applications**

- Control Counters
- Timers
- Frequency Dividers
- Time-Delay Circuits

**Description**

CD4020BMS - 14 Stage  
 CD4024BMS - 7 Stage  
 CD4040BMS - 12 Stage

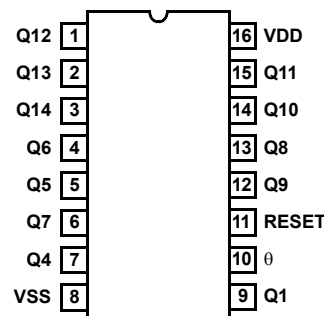
CD4020BMS, CD4024BMS, and CD4040BMS are ripple-carry binary counters. All counter stages are master-slave flip-flops. The state of a counter advances one count on the negative transition of each input pulse; a high level on the RESET line resets the counter to its all zeros state. Schmitt trigger action on the input-pulse line permits unlimited rise and fall times. All inputs and outputs are buffered.

The CD4020BMS, CD4024BMS and the CD4040BMS is supplied in these 14 lead outline packages:

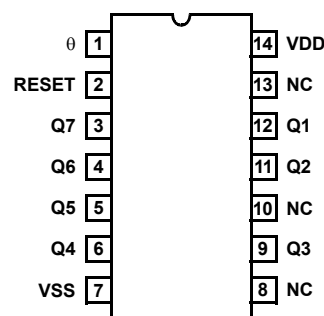
	CD4020B	CD4024B	CD4040B
Braze Seal DIP	H4W	H4Q	H4X
Frit Seal DIP	H1F	H1B	H1F
Ceramic Flatpack	H6W	H3W	H6W

**Pinouts**

CD4020BMS  
TOP VIEW

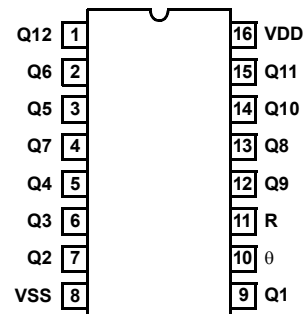


CD4024BMS  
TOP VIEW



NC = NO CONNECTION

CD4040BMS  
TOP VIEW



**Absolute Maximum Ratings**

DC Supply Voltage Range, (VDD).....-0.5V to +20V  
 (Voltage Referenced to VSS Terminals)  
 Input Voltage Range, All Inputs .....-0.5V to VDD +0.5V  
 DC Input Current, Any One Input .....±10mA  
 Operating Temperature Range .....-55°C to +125°C  
 Package Types D, F, K, H  
 Storage Temperature Range (TSTG) .....-65°C to +150°C  
 Lead Temperature (During Soldering).....+265°C  
 At Distance 1/16 ± 1/32 Inch (1.59mm ± 0.79mm) from case for 10s  
 Maximum

**Reliability Information**

Thermal Resistance .....  $\theta_{ja}$   $\theta_{jc}$   
 Ceramic DIP and FRIT Package..... 80°C/W 20°C/W  
 Flatpack Package ..... 70°C/W 20°C/W  
 Maximum Package Power Dissipation (PD) at +125°C  
 For TA = -55°C to +100°C (Package Type D, F, K) ..... 500mW  
 For TA = +100°C to +125°C (Package Type D, F, K)..... Derate  
 Linearity at 12mW/°C to 200mW  
 Device Dissipation per Output Transistor ..... 100mW  
 For TA = Full Package Temperature Range (All Package Types)  
 Junction Temperature..... +175°C

**TABLE 1. DC ELECTRICAL PERFORMANCE CHARACTERISTICS**

PARAMETER	SYMBOL	CONDITIONS (NOTE 1)		GROUP A SUBGROUPS	TEMPERATURE	LIMITS		UNITS
						MIN	MAX	
Supply Current	IDD	VDD = 20V, VIN = VDD or GND		1	+25°C	-	10	µA
				2	+125°C	-	1000	µA
		VDD = 18V, VIN = VDD or GND		3	-55°C	-	10	µA
Input Leakage Current	IIL	VIN = VDD or GND	VDD = 20	1	+25°C	-100	-	nA
			VDD = 18V	2	+125°C	-1000	-	nA
				3	-55°C	-100	-	nA
Input Leakage Current	IIH	VIN = VDD or GND	VDD = 20	1	+25°C	-	100	nA
			VDD = 18V	2	+125°C	-	1000	nA
				3	-55°C	-	100	nA
Output Voltage	VOL15	VDD = 15V, No Load		1, 2, 3	+25°C, +125°C, -55°C	-	50	mV
Output Voltage	VOH15	VDD = 15V, No Load (Note 3)		1, 2, 3	+25°C, +125°C, -55°C	14.95	-	V
Output Current (Sink)	IOL5	VDD = 5V, VOUT = 0.4V		1	+25°C	0.53	-	mA
Output Current (Sink)	IOL10	VDD = 10V, VOUT = 0.5V		1	+25°C	1.4	-	mA
Output Current (Sink)	IOL15	VDD = 15V, VOUT = 1.5V		1	+25°C	3.5	-	mA
Output Current (Source)	IOH5A	VDD = 5V, VOUT = 4.6V		1	+25°C	-	-0.53	mA
Output Current (Source)	IOH5B	VDD = 5V, VOUT = 2.5V		1	+25°C	-	-1.8	mA
Output Current (Source)	IOH10	VDD = 10V, VOUT = 9.5V		1	+25°C	-	-1.4	mA
Output Current (Source)	IOH15	VDD = 15V, VOUT = 13.5V		1	+25°C	-	-3.5	mA
N Threshold Voltage	VNTH	VDD = 10V, ISS = -10µA		1	+25°C	-2.8	-0.7	V
P Threshold Voltage	VPTH	VSS = 0V, IDD = 10µA		1	+25°C	0.7	2.8	V
Functional	F	VDD = 2.8V, VIN = VDD or GND		7	+25°C	VOH > VDD/2	VOL < VDD/2	V
		VDD = 20V, VIN = VDD or GND		7	+25°C			
		VDD = 18V, VIN = VDD or GND		8A	+125°C			
		VDD = 3V, VIN = VDD or GND		8B	-55°C			
Input Voltage Low (Note 2)	VIL	VDD = 5V, VOH > 4.5V, VOL < 0.5V		1, 2, 3	+25°C, +125°C, -55°C	-	1.5	V
Input Voltage High (Note 2)	VIH	VDD = 5V, VOH > 4.5V, VOL < 0.5V		1, 2, 3	+25°C, +125°C, -55°C	3.5	-	V
Input Voltage Low (Note 2)	VIL	VDD = 15V, VOH > 13.5V, VOL < 1.5V		1, 2, 3	+25°C, +125°C, -55°C	-	4	V
Input Voltage High (Note 2)	VIH	VDD = 15V, VOH > 13.5V, VOL < 1.5V		1, 2, 3	+25°C, +125°C, -55°C	11	-	V

TABLE 1. DC ELECTRICAL PERFORMANCE CHARACTERISTICS

PARAMETER	SYMBOL	CONDITIONS (NOTE 1)	GROUP A SUBGROUPS	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	

NOTES: 1. All voltages referenced to device GND, 100% testing being implemented. 2. Go/No Go test with limits applied to inputs 3. For accuracy, voltage is measured differentially to VDD. Limit is 0.050V max.

TABLE 2. AC ELECTRICAL PERFORMANCE CHARACTERISTICS

PARAMETER	SYMBOL	CONDITIONS (NOTE 1, 2)	GROUP A SUBGROUPS	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	
Propagation Delay 0 To Q1	TPHL1 TPLH1	VDD = 5V, VIN = VDD or GND	9	+25°C	-	360	ns
			10, 11	+125°C, -55°C	-	486	ns
Propagation Delay Qn To Qn + 1	TPHL2 TPLH2	VDD = 5V, VIN = VDD or GND	9	+25°C	-	330	ns
			10, 11	+125°C, -55°C	-	446	ns
Propagation Delay Reset To Q	TPLH3 TPHL3	VDD = 5V, VIN = VDD or GND	9	+25°C	-	280	ns
			10, 11	+125°C, -55°C	-	378	ns
Transition Time Q1	TTHL TTLH	VDD = 5V, VIN = VDD or GND	9	+25°C	-	200	ns
			10, 11	+125°C, -55°C	-	270	ns
Maximum Clock Input Frequency	FCL	VDD = 5V, VIN = VDD or GND	9	+25°C	3.5	-	MHz
			10, 11	+125°C, -55°C	2.22	-	MHz

NOTES:

- VDD = 5V, CL = 50pF, RL = 200K
- 55°C and +125°C limits guaranteed, 100% testing being implemented.

TABLE 3. ELECTRICAL PERFORMANCE CHARACTERISTICS

PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	
Supply Current	IDD	VDD = 5V, VIN = VDD or GND	1, 2	-55°C, +25°C	-	5	μA
				+125°C	-	150	μA
		VDD = 10V, VIN = VDD or GND	1, 2	-55°C, +25°C	-	10	μA
				+125°C	-	300	μA
		VDD = 15V, VIN = VDD or GND	1, 2	-55°C, +25°C	-	10	μA
+125°C	-			600	μA		
Output Voltage	VOL	VDD = 5V, No Load	1, 2	+25°C, +125°C, -55°C	-	50	mV
Output Voltage	VOL	VDD = 10V, No Load	1, 2	+25°C, +125°C, -55°C	-	50	mV
Output Voltage	VOH	VDD = 5V, No Load	1, 2	+25°C, +125°C, -55°C	4.95	-	V
Output Voltage	VOH	VDD = 10V, No Load	1, 2	+25°C, +125°C, -55°C	9.95	-	V
Output Current (Sink)	IOL5	VDD = 5V, VOUT = 0.4V	1, 2	+125°C	0.36	-	mA
				-55°C	0.64	-	mA
Output Current (Sink)	IOL10	VDD = 10V, VOUT = 0.5V	1, 2	+125°C	0.9	-	mA
				-55°C	1.6	-	mA
Output Current (Sink)	IOL15	VDD = 15V, VOUT = 1.5V	1, 2	+125°C	2.4	-	mA
				-55°C	4.2	-	mA

**TABLE 3. ELECTRICAL PERFORMANCE CHARACTERISTICS (Continued)**

PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	
Output Current (Source)	IOH5A	VDD = 5V, VOUT = 4.6V	1, 2	+125°C	-	-0.36	mA
				-55°C	-	-0.64	mA
Output Current (Source)	IOH5B	VDD = 5V, VOUT = 2.5V	1, 2	+125°C	-	-1.15	mA
				-55°C	-	-2.0	mA
Output Current (Source)	IOH10	VDD = 10V, VOUT = 9.5V	1, 2	+125°C	-	-0.9	mA
				-55°C	-	-1.6	mA
Output Current (Source)	IOH15	VDD = 15V, VOUT = 13.5V	1, 2	+125°C	-	-2.4	mA
				-55°C	-	-4.2	mA
Input Voltage Low	VIL	VDD = 10V, VOH > 9V, VOL < 1V	1, 2	+25°C, +125°C, -55°C	-	3	V
Input Voltage High	VIH	VDD = 10V, VOH > 9V, VOL < 1V	1, 2	+25°C, +125°C, -55°C	7	-	V
Propagation Delay Input To Q1	TPHL1 TPLH1	VDD = 10V	1, 2, 3	+25°C	-	160	ns
		VDD = 15V	1, 2, 3	+25°C	-	130	ns
Propagation Delay QN To QN + 1	TPHL2 TPLH2	VDD = 10V	1, 2, 3	+25°C	-	80	ns
		VDD = 15V	1, 2, 3	+25°C	-	60	ns
Propagation Delay Reset To Q	TPHL3	VDD = 10V	1, 2, 3	+25°C	-	120	ns
		VDD = 15V	1, 2, 3	+25°C	-	100	ns
Transition Time	TTHL TTLH	VDD = 10V	2, 3	+25°C	-	100	ns
		VDD = 15V	2, 3	+25°C	-	80	ns
Maximum Clock Input Frequency	FCL	VDD = 10V	1, 2, 3	+25°C	8	-	MHz
		VDD = 15V	1, 2, 3	+25°C	12	-	MHz
Minimum Reset Pulse Width	TW	VDD = 5V	1, 2, 3	+25°C	-	200	ns
		VDD = 10V	1, 2, 3	+25°C	-	80	ns
		VDD = 15V	1, 2, 3	+25°C	-	60	ns
Reset Removal Time	TREM	VDD = 5V	1, 2, 3	+25°C	-	350	ns
		VDD = 10V	1, 2, 3	+25°C	-	150	ns
		VDD = 15V	1, 2, 3	+25°C	-	100	ns
Minimum Input Pulse Width	TW	VDD = 5V	1, 2, 3	+25°C	-	140	ns
		VDD = 10V	1, 2, 3	+25°C	-	60	ns
		VDD = 15V	1, 2, 3	+25°C	-	40	ns
Input Capacitance	CIN	Any Input	1, 2	+25°C	-	7.5	pF

NOTES:

1. All voltages referenced to device GND.
2. The parameters listed on Table 3 are controlled via design or process and are not directly tested. These parameters are characterized on initial design release and upon design changes which would affect these characteristics.
3. CL = 50pF, RL = 200K, Input TR, TF < 20ns.

**TABLE 4. POST IRRADIATION ELECTRICAL PERFORMANCE CHARACTERISTICS**

PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	
Supply Current	IDD	VDD = 20V, VIN = VDD or GND	1, 4	+25°C	-	25	μA
N Threshold Voltage	VNTH	VDD = 10V, ISS = -10μA	1, 4	+25°C	-2.8	-0.2	V

**TABLE 4. POST IRRADIATION ELECTRICAL PERFORMANCE CHARACTERISTICS (Continued)**

PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	
N Threshold Voltage Delta	$\Delta V_{TND}$	VDD = 10V, ISS = -10 $\mu$ A	1, 4	+25°C	-	$\pm 1$	V
P Threshold Voltage	VTP	VSS = 0V, IDD = 10 $\mu$ A	1, 4	+25°C	0.2	2.8	V
P Threshold Voltage Delta	$\Delta V_{TPD}$	VSS = 0V, IDD = 10 $\mu$ A	1, 4	+25°C	-	$\pm 1$	V
Functional	F	VDD = 18V, VIN = VDD or GND	1	+25°C	VOH > VDD/2	VOL < VDD/2	V
		VDD = 3V, VIN = VDD or GND					
Propagation Delay Time	TPHL TPLH	VDD = 5V	1, 2, 3, 4	+25°C	-	1.35 x +25°C Limit	ns

NOTES: 1. All voltages referenced to device GND. 2. CL = 50pF, RL = 200K, Input TR, TF < 20ns. 3. See Table 2 for +25°C limit. 4. Read and Record

**TABLE 5. BURN-IN AND LIFE TEST DELTA PARAMETERS +25°C**

PARAMETER	SYMBOL	DELTA LIMIT
Supply Current - MSI-2	IDD	$\pm 1.0\mu$ A
Output Current (Sink)	IOL5	$\pm 20\%$ x Pre-Test Reading
Output Current (Source)	IOH5A	$\pm 20\%$ x Pre-Test Reading

**TABLE 6. APPLICABLE SUBGROUPS**

CONFORMANCE GROUP	MIL-STD-883 METHOD	GROUP A SUBGROUPS	READ AND RECORD
Initial Test (Pre Burn-In)	100% 5004	1, 7, 9	IDD, IOL5, IOH5A
Interim Test 1 (Post Burn-In)	100% 5004	1, 7, 9	IDD, IOL5, IOH5A
Interim Test 2 (Post Burn-In)	100% 5004	1, 7, 9	IDD, IOL5, IOH5A
PDA (Note 1)	100% 5004	1, 7, 9, Deltas	
Interim Test 3 (Post Burn-In)	100% 5004	1, 7, 9	IDD, IOL5, IOH5A
PDA (Note 1)	100% 5004	1, 7, 9, Deltas	
Final Test	100% 5004	2, 3, 8A, 8B, 10, 11	
Group A	Sample 5005	1, 2, 3, 7, 8A, 8B, 9, 10, 11	
Group B	Subgroup B-5	1, 2, 3, 7, 8A, 8B, 9, 10, 11, Deltas	Subgroups 1, 2, 3, 9, 10, 11
	Subgroup B-6	1, 7, 9	
Group D	Sample 5005	1, 2, 3, 8A, 8B, 9	Subgroups 1, 2, 3

NOTE: 1. 5% Parametric, 3% Functional; Cumulative for Static 1 and 2.

**TABLE 7. TOTAL DOSE IRRADIATION**

CONFORMANCE GROUPS	MIL-STD-883 METHOD	TEST		READ AND RECORD	
		PRE-IRRAD	POST-IRRAD	PRE-IRRAD	POST-IRRAD
Group E Subgroup 2	5005	1, 7, 9	Table 4	1, 9	Table 4

**TABLE 8. BURN-IN AND IRRADIATION TEST CONNECTIONS**

FUNCTION	OPEN	GROUND	VDD	9V $\pm$ -0.5V	OSCILLATOR	
					50kHz	25kHz
PART NUMBER CD4020BMS						

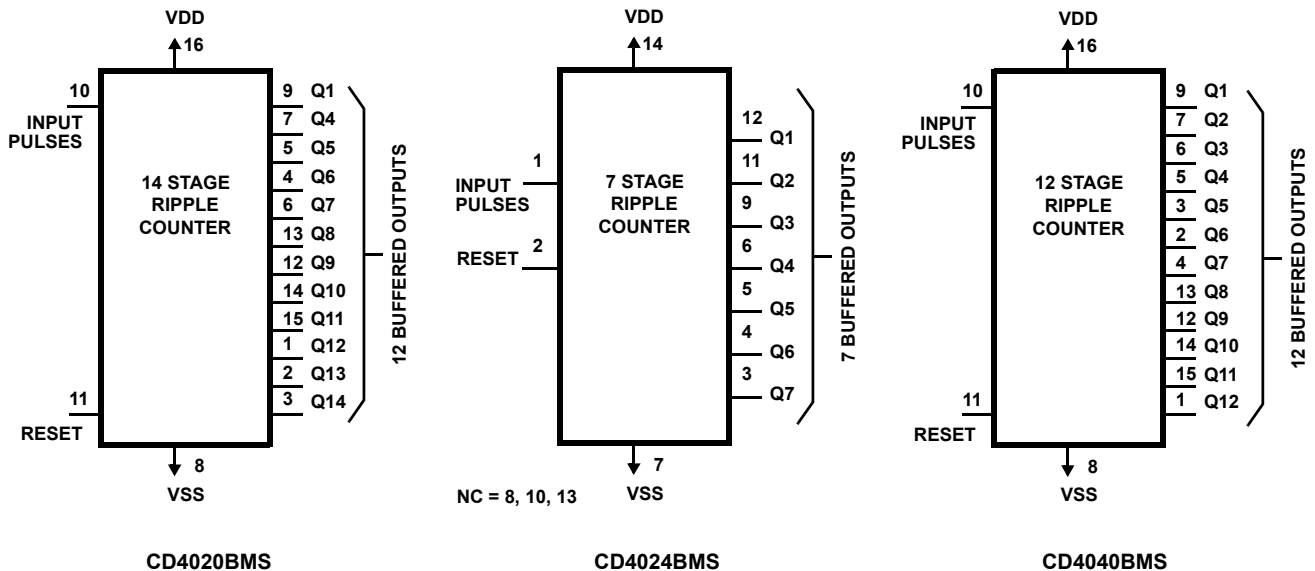
TABLE 8. BURN-IN AND IRRADIATION TEST CONNECTIONS (Continued)

FUNCTION	OPEN	GROUND	VDD	9V ± -0.5V	OSCILLATOR	
					50kHz	25kHz
Static Burn-In 1 Note 1	1 - 7, 9, 12 - 15	8, 10, 11	16			
Static Burn-In 2 Note 1	1 - 7, 9, 12 - 15	8	10, 11, 16			
Dynamic Burn-In Note 1	-	8, 11	16	1 - 7, 9, 12 - 15	10	
Irradiation Note 2	1 - 7, 9, 12 - 15	8	10, 11, 16			
PART NUMBER CD4024BMS						
Static Burn-In 1 Note 1	3 - 6, 8 - 13	1, 2, 7	14			
Static Burn-In 2 Note 1	3 - 6, 8 - 13	7	1, 2, 14			
Dynamic Burn-In Note 1	8, 10, 13	2, 7	14	3 - 6, 9, 11, 12	1	
Irradiation Note 2	3 - 6, 8 - 13	7	1, 2, 14			
PART NUMBER CD4040BMS						
Static Burn-In 1 Note 1	1 - 7, 9, 12 - 15	8, 10, 11	16			
Static Burn-In 2 Note 1	1 - 7, 9, 12 - 15	8	10, 11, 16			
Dynamic Burn-In Note 1	-	8, 11	16	1 - 7, 9, 12 - 15	10	
Irradiation Note 2	1 - 7, 9, 12 - 15	8	10, 11, 16			

NOTE:

1. Each pin except VDD and GND will have a series resistor of 10K ± 5%, VDD = 18V ± 0.5V
2. Each pin except VDD and GND will have a series resistor of 47K ± 5%; Group E, Subgroup 2, sample size is 4 dice/wafer, 0 failures, VDD = 10V ± 0.5V

Functional Diagrams



**Logic Diagrams**

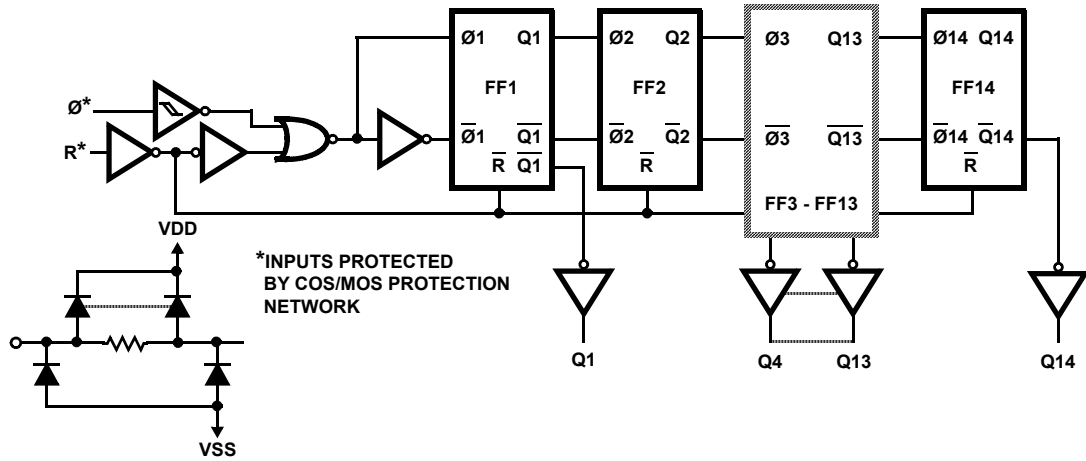


FIGURE 1. LOGIC DIAGRAM FOR CD4020BMS

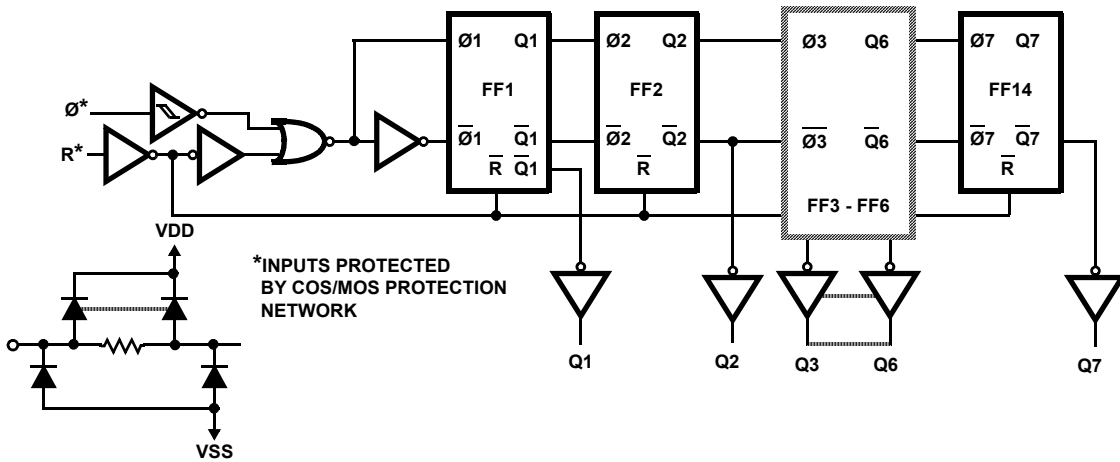


FIGURE 2. LOGIC DIAGRAM FOR CD4024BMS

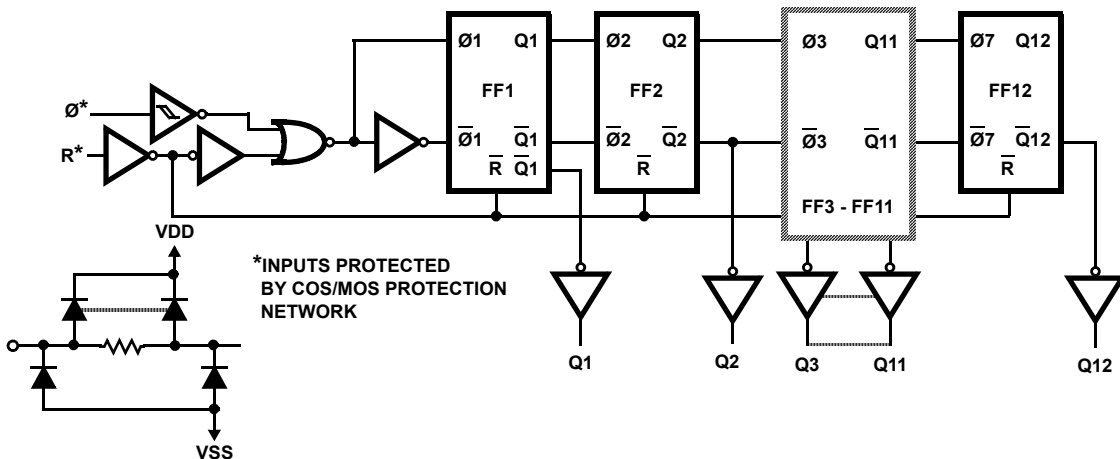


FIGURE 3. LOGIC DIAGRAM FOR CD4040BMS

**Typical Performance Characteristics**

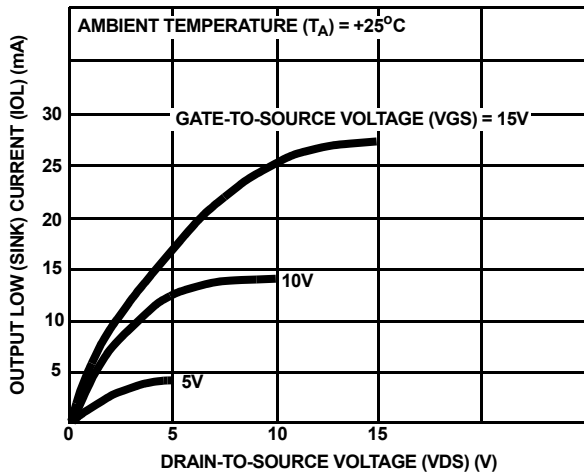


FIGURE 4. TYPICAL OUTPUT LOW (SINK) CURRENT CHARACTERISTICS

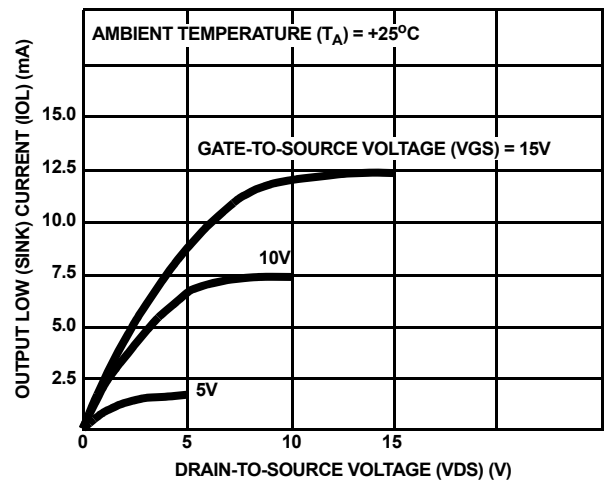


FIGURE 5. MINIMUM OUTPUT LOW (SINK) CURRENT CHARACTERISTICS

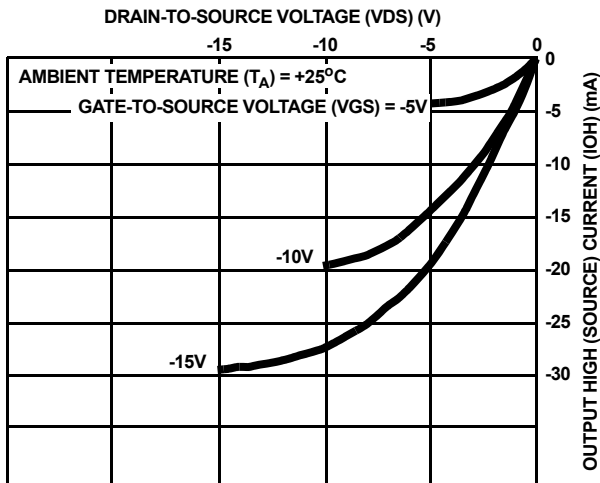


FIGURE 6. TYPICAL OUTPUT HIGH (SOURCE) CURRENT CHARACTERISTICS

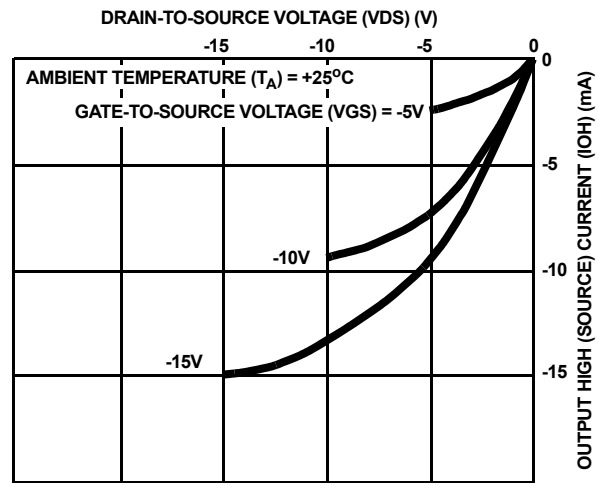


FIGURE 7. MINIMUM OUTPUT HIGH (SOURCE) CURRENT CHARACTERISTICS



**Typical Performance Characteristics** (Continued)

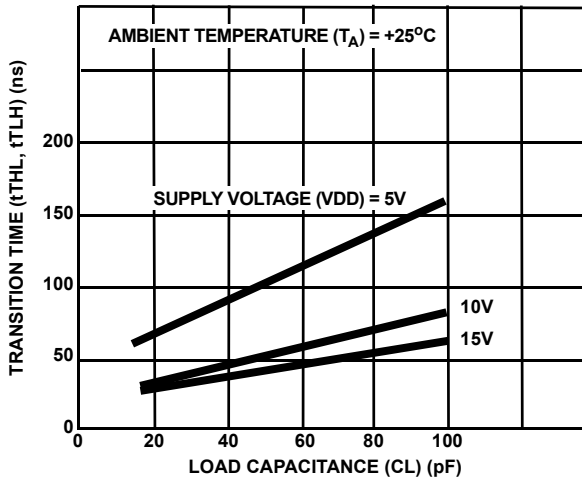


FIGURE 8. TYPICAL TRANSITION TIME AS A FUNCTION OF LOAD CAPACITANCE

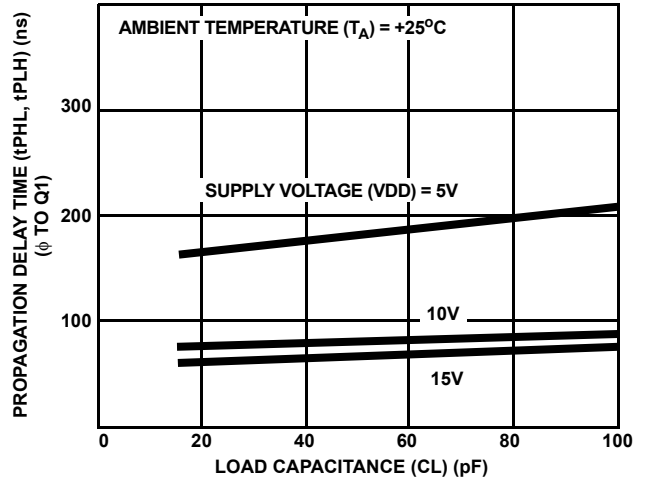


FIGURE 9. TYPICAL PROPAGATION DELAY TIME AS A FUNCTION OF LOAD CAPACITANCE ( $\phi$  TO Q1)

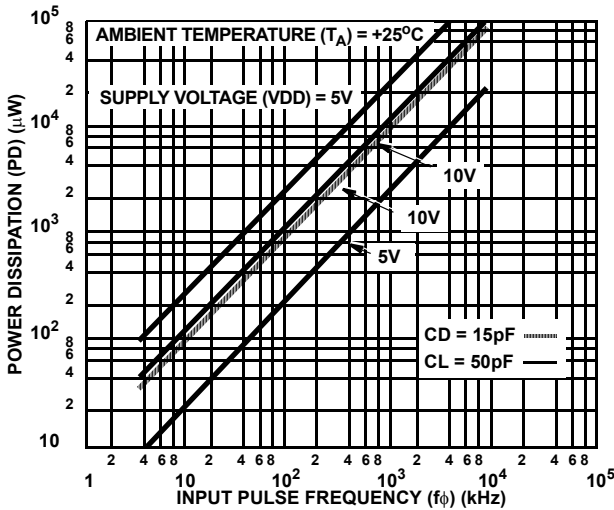
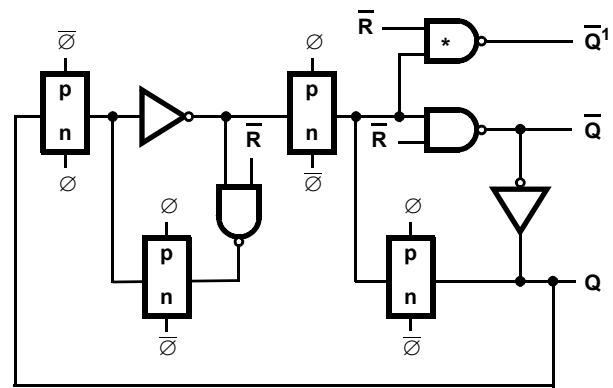


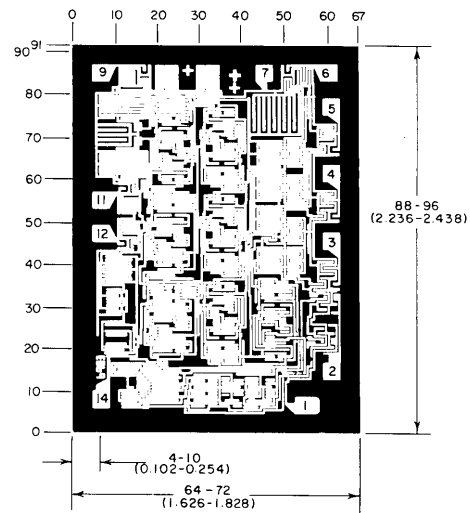
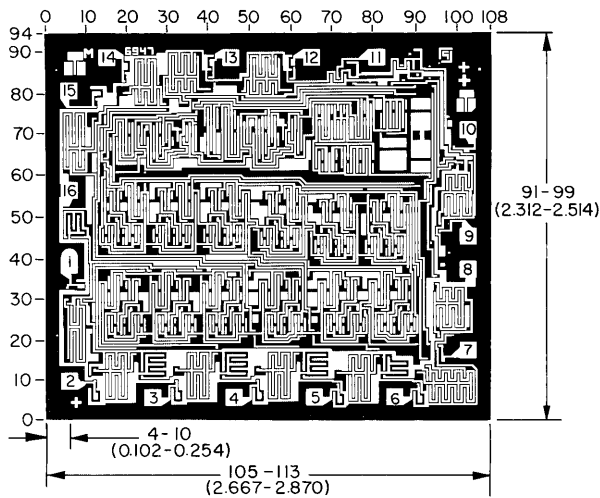
FIGURE 10. TYPICAL DYNAMIC POWER DISSIPATION AS A FUNCTION OF INPUT PULSE FREQUENCY FOR CD4020BMS



\* ON FIRST STAGE ONLY

FIGURE 11. DETAIL OF TYPICAL FLIP-FLOP STAGES

## Chip Dimensions and Pad Layouts



Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils ( $10^{-3}$  inch)

**DIMENSIONS AND PAD LAYOUT FOR CD4020BMS. DIMENSIONS AND PAD LAYOUT FOR CD4040BMS ARE IDENTICAL**

**DIMENSIONS AND PAD LAYOUT FOR CD4024BMSH**

**METALLIZATION:** Thickness:  $11\text{k}\text{\AA} - 14\text{k}\text{\AA}$ , AL.

**PASSIVATION:**  $10.4\text{k}\text{\AA} - 15.6\text{k}\text{\AA}$ , Silane

**BOND PADS:** 0.004 inches X 0.004 inches MIN

**DIE THICKNESS:** 0.0198 inches - 0.0218 inches

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